

AIM 58Bi/42Sn Solder for Photonic Packaging

Category : Metal , Nonferrous Metal , Bismuth Alloy , Solder/Braze Alloy

Material Notes:

Uses include:Fiber to Ferrule SolderingLaser Die AttachHermetic Packaging & SealingWetting & Sealing Laser OpticsThermal ManagementInformation provided by AIM Specialty Materials.

Order this product through the following link:

http://www.lookpolymers.com/polymer_AIM-58Bi42Sn-Solder-for-Photonic-Packaging.php

Physical Properties	Metric	English	Comments
Density	8.56 g/cc	0.309 lb/in ³	

Mechanical Properties	Metric	English	Comments
Tensile Strength, Ultimate	379 MPa	55000 psi	

Thermal Properties	Metric	English	Comments
CTE, linear	14.0 $\mu\text{m}/\text{m}\cdot\text{°C}$	7.78 $\mu\text{in}/\text{in}\cdot\text{°F}$	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Melting Point	138 °C	280 °F	
Solidus	138 °C	280 °F	
Liquidus	138 °C	280 °F	

Component Elements Properties	Metric	English	Comments
Bismuth, Bi	58 %	58 %	
Tin, Sn	42 %	42 %	

Descriptive Properties	Value	Comments
Creep Resistance	Moderate	

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